



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-07-21
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS30120DJF-TR	7SER*Z75P15Z	A	3068	2017-07-21
	Amount	UoM	Unit type	ST ECOPACK Grade
	95.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5-6-0.8	12	Flat	
Comment	Power FLAT 5x6 8L SINGLE			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.07	die backside metal- leadframe metal	726
Lead	5.65	soft solder	59516

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	7SER*275P15Z					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.064	mg	supplier	die	Silicon (Si)	7440-21-3		4.567	mg	901856	48074
				supplier	metallization	Aluminium (Al)	7429-90-5		0.265	mg	52330	2789
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	1186	63
				supplier	metallization	Tungsten (W)	7440-33-7		0.010	mg	1975	105
				supplier	Passivation	Silicon Oxide	7631-86-9		0.039	mg	7701	411
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	592	32
				supplier	back side metallization	Gold (Au)	7440-57-5		0.009	mg	1777	95
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.044	mg	8689	463
				supplier	polymer die coating	Durimide	proprietary		0.121	mg	23894	1274
				supplier	alloy	Copper (Cu)	7440-50-8		47.785	mg	973952	503000
Leadframe	Copper & its alloys	49.063	mg	supplier	alloy	Iron (Fe)	7439-89-6		1.124	mg	22909	11832
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.068	mg	1386	716
				supplier	alloy	Zinc (Zn)	7440-66-6		0.059	mg	1203	620
				supplier	metallization	Nickel (Ni)	7440-02-0		0.025	mg	510	263
				supplier	metallization	Phosphorus (P)	12185-10-3		0.002	mg	40	21
				supplier	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	5.654	mg	955068
Soft solder	Solder	5.920	mg	supplier	solder	Silver (Ag)	7440-22-4		0.148	mg	25000	1558
				supplier	solder	Tin (Sn)	7440-31-5		0.118	mg	19932	1242
				supplier	Ribbon	Aluminium (Al)	7429-90-5		1.282	mg	1000000	13495
Bonding Ribbons	Other Nonferrous metals & alloys	1.282	mg	supplier	mold compound	Silica, vitreous	60676-86-0		31.041	mg	925989	326747
				supplier	mold compound	epoxy resin	85954-11-6		1.341	mg	40004	14116
				supplier	mold compound	phenol resin	26834-02-6		1.006	mg	30010	10589
				supplier	mold compound	carbon black	1333-86-4		0.134	mg	3997	1411
Encapsulation	Other Organic Materials	33.522	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.149	mg	1000000	1568
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.149	mg	1000000	1568
Connections coating	Solder	0.149	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.149	mg	1000000	1568